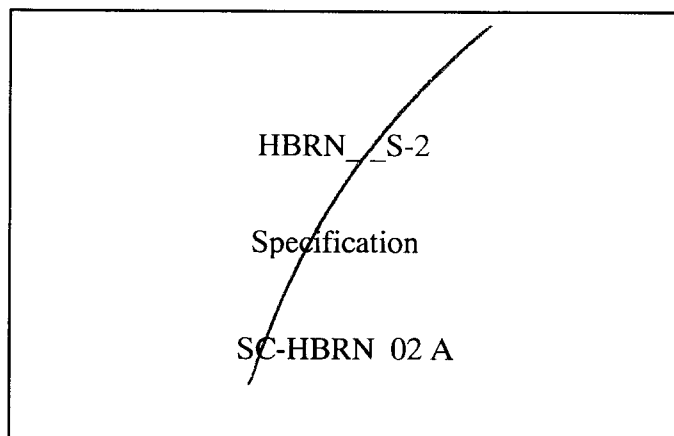


Ref. No. 000771

2000/10

SPEC ON WEB SITE
UNDER SEPARATE
COVER



Drawing No.

JSA28712-1

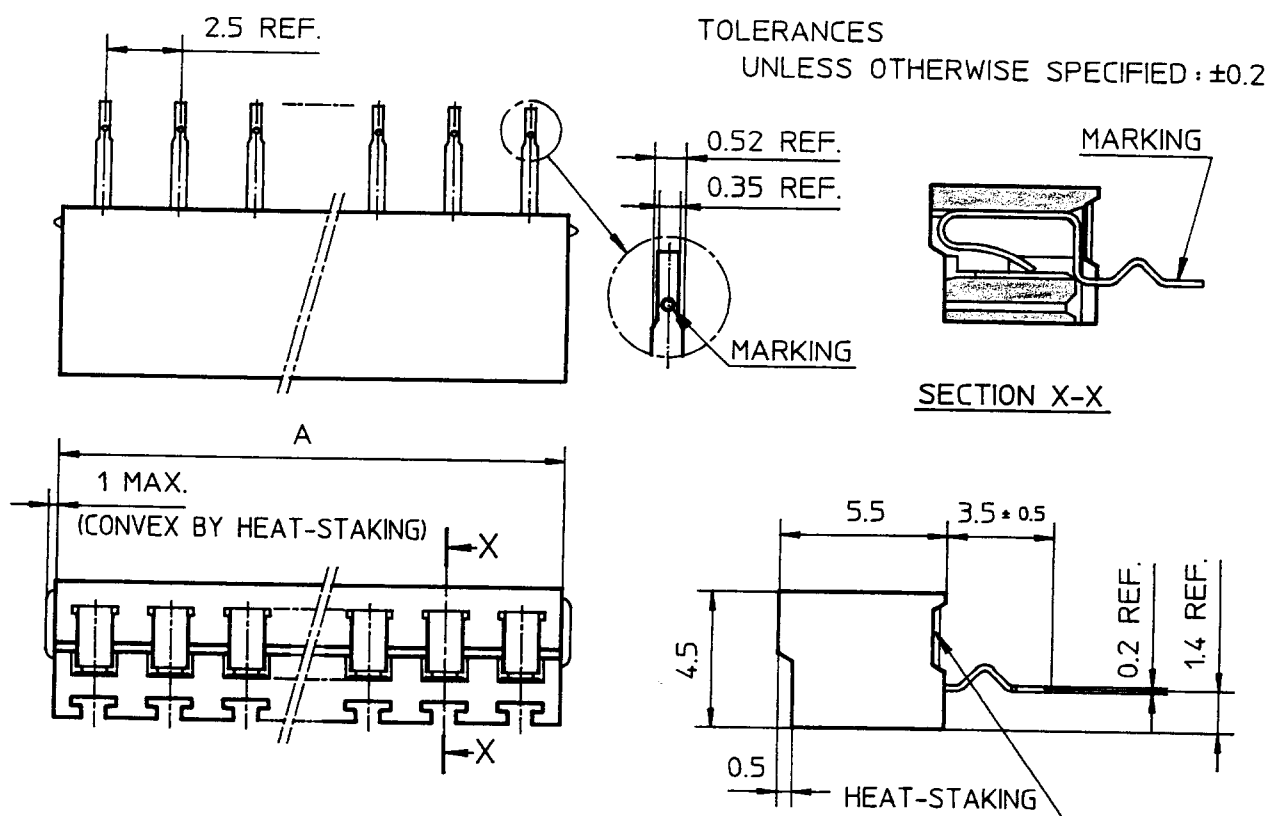
FCI Japan K. K.

Electronics Division Engineering Section

Certified by H. Takakura

H. Takakura

Manager, Engineering Section

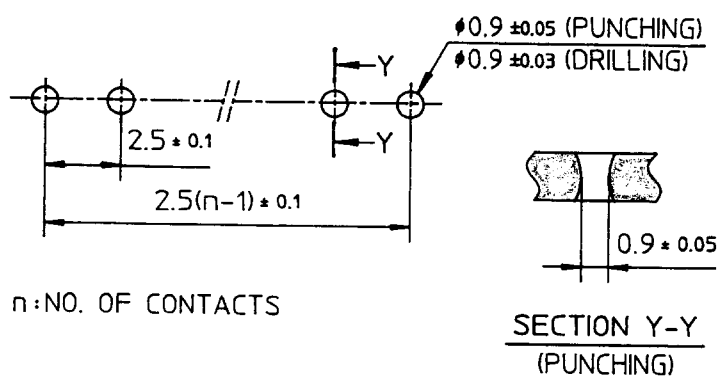


MATERIAL

INSULATOR : PBT RESIN
GLASS REINFORCED (UL94V-0)
COLOR : BLACK
CONTACT : PHOSPHOR BRONZE
(TIN ALLOY PLATED)

RECOMMENDED PC BOARD

THICKNESS : 1.2, 1.6
HOLE PATTERN (COMPONENT SIDE)



CAT. NO.	DIMENSIONS
	A MAX.
HBRN2S-2	5.0
HBRN3S-2	7.5
HBRN4S-2	10.0
HBRN5S-2	12.5
HBRN6S-2	15.0
HBRN7S-2	17.5
HBRN8S-2	20.0
HBRN9S-2	22.5
HBRN10S-2	25.0
HBRN11S-2	27.5
HBRN12S-2	30.0
HBRN13S-2	32.5
HBRN14S-2	35.0
HBRN15S-2	37.5

				SCALE	$\times$	WIREMATE CONNECTOR FOR 2.5mm SPACING FRC	
				DIM. IN	mm	CAT. NO.	
1	JUN. 1'98	REDRAWN M.I	H.T	DESIGNED	M.Takada	HBRN__S-2	
REV.	DATE	DESCRIPTION	CKD.	DRAWN	H.Sunagawa	DRAWING NO.	REV.
MATERIAL				CHECKED		JSA 28712	1
				APPROVED	A.NAKAI	 FRAMATOME GROUP	
				DATE	Oct. 13, 1986		